

MOSFETs Silicon N-channel MOS (U-MOSIX-H)

XPH3R304PB

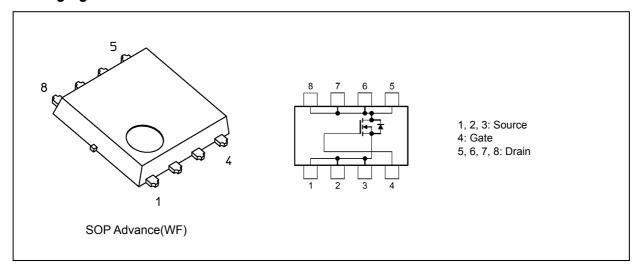
1. Applications

- · Automotive
- · Motor Drivers
- · Switching Voltage Regulators

2. Features

- (1) AEC-Q101 qualified
- (2) Small, thin package
- (3) Low drain-source on-resistance: $R_{DS(ON)} = 2.5 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (4) Low leakage current: I_{DSS} = 10 μA (max) (V_{DS} = 40 V)
- (5) Enhancement mode: $V_{th} = 2.0 \text{ to } 3.0 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 0.2 \text{ mA})$

3. Packaging and Internal Circuit



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4. Absolute Maximum Ratings (Note) (T_a = 25 °C unless otherwise specified)

Characteris	stics		Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	40	V
Gate-source voltage			V _{GSS}	+20/-8	
Drain current (DC)		(Note 1)	I _D	60	Α
Drain current (pulsed)		(Note 1)	I _{DP}	120	
Power dissipation	(T _c = 25 °C)		P _D	76	W
Power dissipation	(t = 10 s)	(Note 2)		3.0	1
Power dissipation	(t = 10 s)	(Note 3)		0.96	
Single-pulse avalanche energy		(Note 4)	E _{AS}	62	mJ
Single-pulse avalanche current			I _{AS}	30	Α
Channel temperature		(Note 5)	T _{ch}	175	°C
Storage temperature		(Note 5)	T _{stg}	-55 to 175	

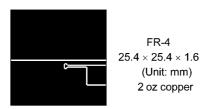
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

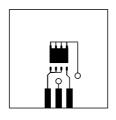
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit		
Channel-to-case thermal impedance	(T _c = 25 °C)		Z _{th(ch-c)}	1.95	°C/W
Channel-to-ambient thermal impedance	(t = 10 s)	(Note 2)	Z _{th(ch-a)}	50	
Channel-to-ambient thermal impedance	(t = 10 s)	(Note 3)	Z _{th(ch-a)}	156	

- Note 1: Ensure that the channel temperature does not exceed 175 °C.
- Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1
- Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2
- Note 4: V_{DD} = 32 V, T_{ch} = 25 °C (initial), L = 53.3 μ H, R_{G} = 25 Ω , I_{AS} = 30 A
- Note 5: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.





FR-4 $25.4 \times 25.4 \times 1.6$ (Unit: mm) 2 oz copper

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V _{GS} = +20/-8 V, V _{DS} = 0 V	_	_	±1	μА
Drain cut-off current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	40	_		٧
	V _{(BR)DSX}	$I_D = 10 \text{ mA}, V_{GS} = -8 \text{ V}$	20	_		
Gate threshold voltage	V_{th}	V_{DS} = 10 V, I_{D} = 0.2 mA	2.0	_	3.0	
Drain-source on-resistance	R _{DS(ON)}	$V_{GS} = 6 \text{ V}, I_D = 30 \text{ A}$	_	3.8	6.3	mΩ
		V _{GS} = 10 V, I _D = 30 A	_	2.5	3.3	

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	1660	_	pF
Reverse transfer capacitance	C _{rss}		_	145	_	
Output capacitance	C _{oss}		_	1040	_	
Gate resistance	r _g		_	1.9	3.8	Ω
Switching time (rise time)	t _r	See Fig. 6.2.1	_	18	_	ns
Switching time (turn-on time)	t _{on}		_	27	_	
Switching time (fall time)	t _f		_	18	_	
Switching time (turn-off time)	t _{off}		_	77	_	

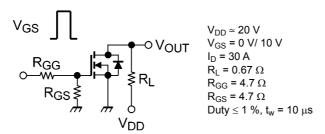


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 32 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 60 \text{ A}$		30	1	nC
Gate-source charge 1	Q _{gs1}		_	11		
Gate-drain charge	Q_{gd}		_	6	_	

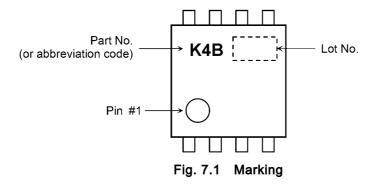
6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (No	te 6)	I _{DRP}	_	_	_	120	Α
Diode forward voltage		V_{DSF}	I _{DR} = 60 A, V _{GS} = 0 V	_	_	-1.2	V

Note 6: Ensure that the channel temperature does not exceed 175 °C.



7. Marking



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8. Characteristics Curves (Note)

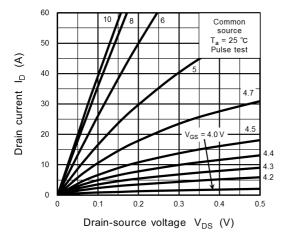


Fig. 8.1 I_D - V_{DS}

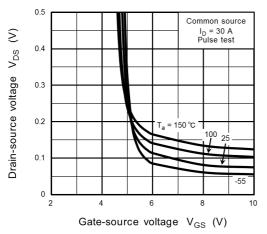


Fig. 8.3 V_{DS} - V_{GS}

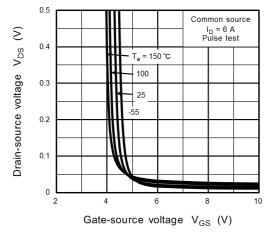


Fig. 8.5 V_{DS} - V_{GS}

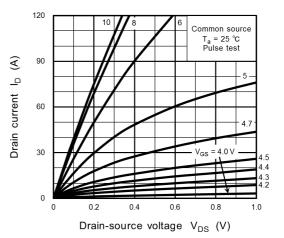


Fig. 8.2 I_D - V_{DS}

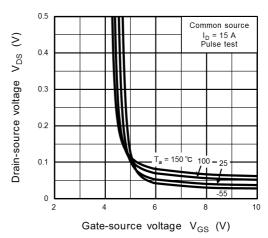


Fig. 8.4 V_{DS} - V_{GS}

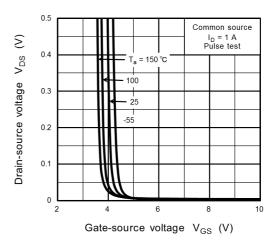


Fig. 8.6 V_{DS} - V_{GS}



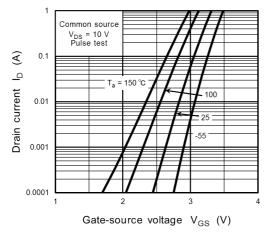


Fig. 8.7 ID - VGS

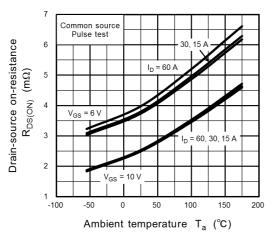


Fig. 8.9 RDS(ON) - Ta

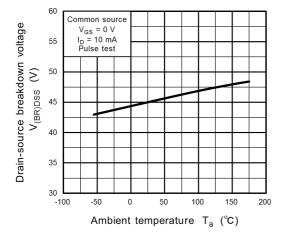


Fig. 8.11 V_{(BR)DSS} - T_a

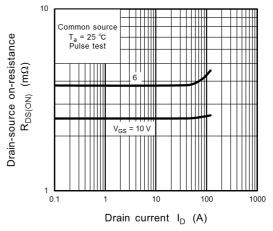


Fig. 8.8 R_{DS(ON)} - I_D

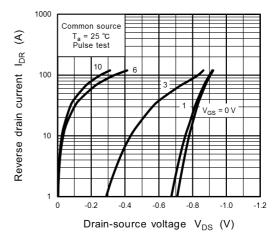


Fig. 8.10 I_{DR} - V_{DS}

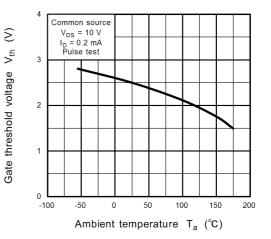


Fig. 8.12 V_{th} - T_a



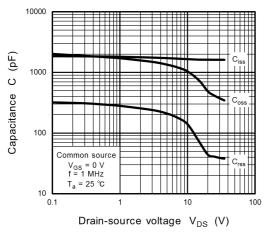


Fig. 8.13 Capacitance - V_{DS}

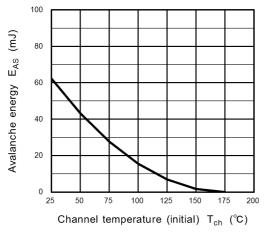


Fig. 8.15 E_{AS} - T_{ch}(Guaranteed Maximum)

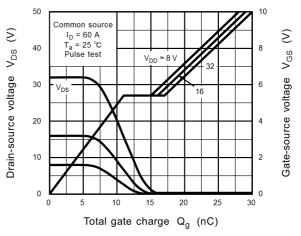


Fig. 8.14 Dynamic Input/Output Characteristics

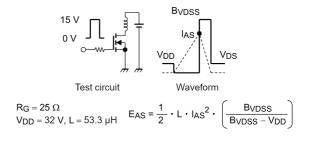


Fig. 8.16 Test Circuit/Waveform



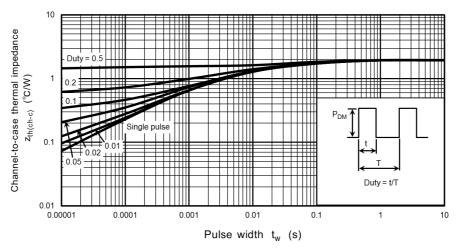
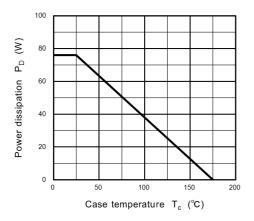


Fig. 8.17 $z_{th(ch-c)}$ - t_w (Guaranteed Maximum)



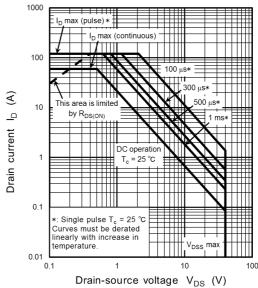


Fig. 8.18 P_D - T_c (Guaranteed Maximum)

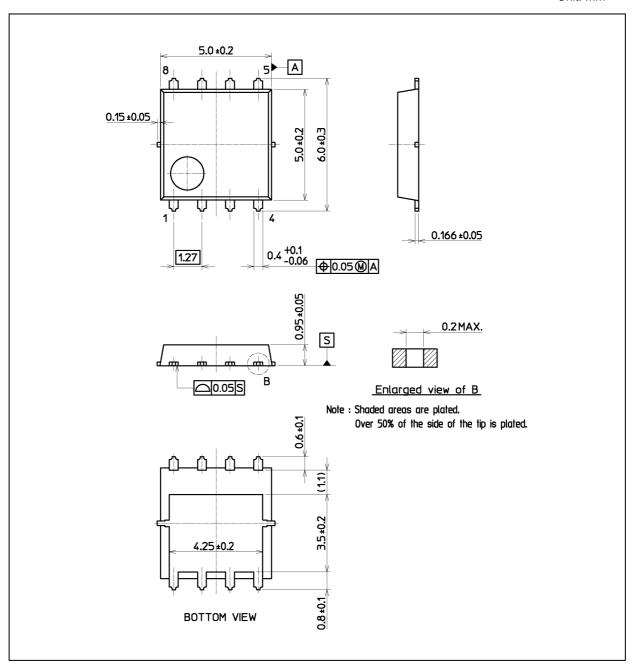
Fig. 8.19 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 0.070 g (typ.)

Package Name(s)
TOSHIBA: 2-5Q4A
Nickname: SOP Advance(WF)



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